



### Features

- DC – 3.0 GHz
- 25 Watts
- Aluminum Nitride (AlN) Ceramic
- Surface Mountable
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

### General Specifications

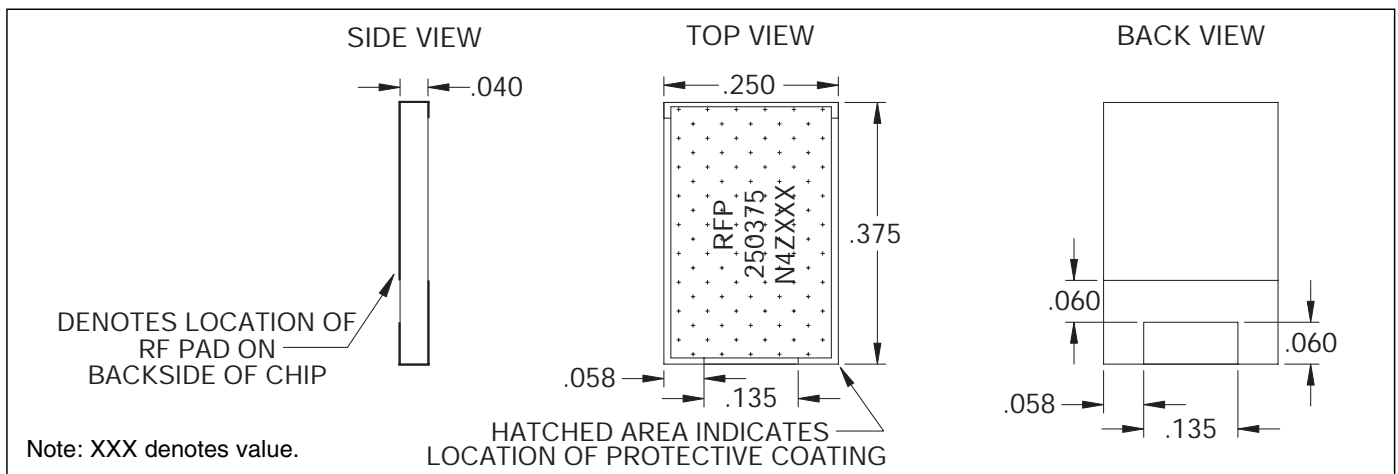
<b>Resistive Element:</b>	Thick film
<b>Substrate:</b>	Aluminum nitride ceramic
<b>Terminals:</b>	Tin/Lead, 90/10 over nickel

### Electrical Specifications

<b>Resistance Value:</b>	50 ohms, ±2%
<b>Frequency Range:</b>	DC - 3.0 GHz
<b>Power:</b>	25 Watts
<b>V.S.W.R.:</b>	1.25:1

**Notes:** Tolerance is ±.010, unless otherwise specified. Operating temperature is -55°C to +125°C (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches.  
**Specifications subject to change without notice.**

### Outline Drawing



Available on Tape and Reel for Pick and Place Manufacturing.

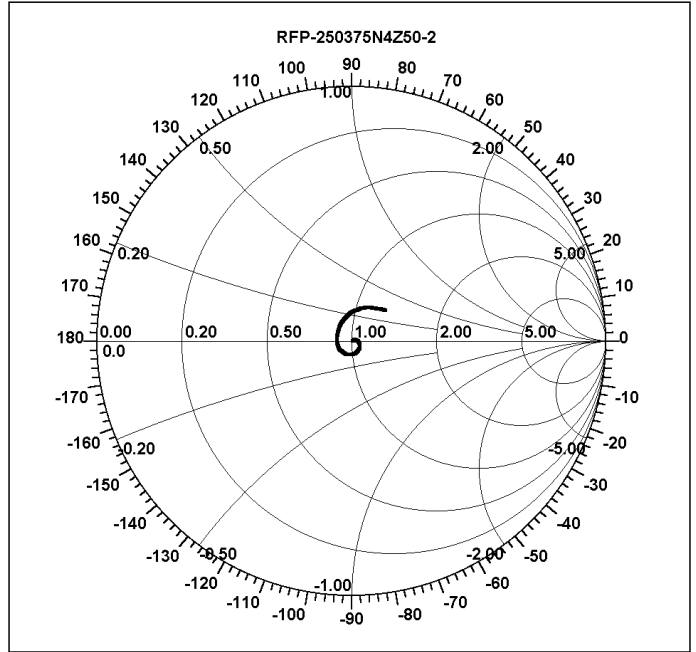
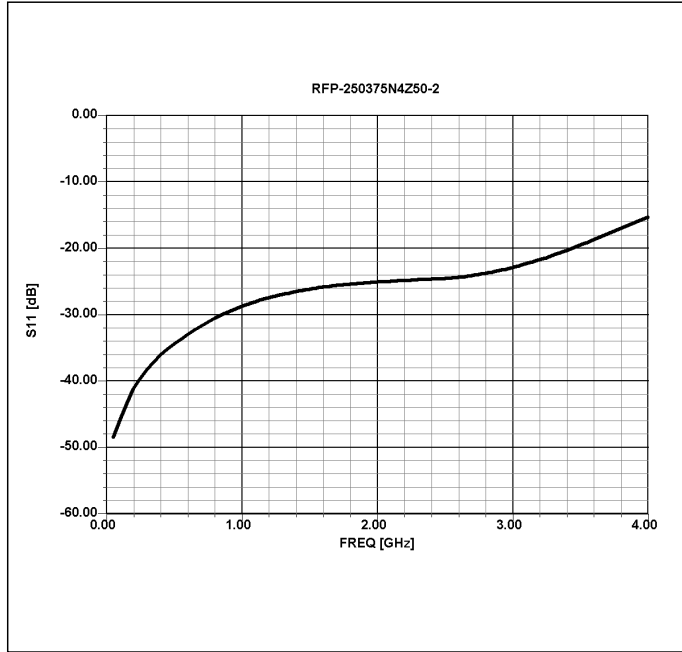
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# Model RFP-250375N4Z50-2

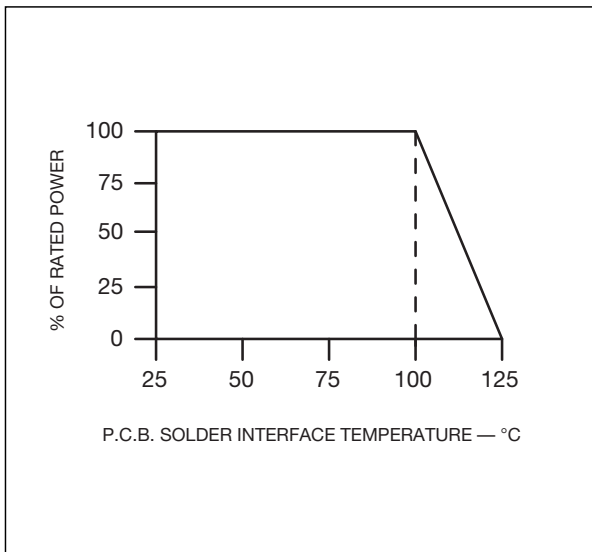


**RF Power**

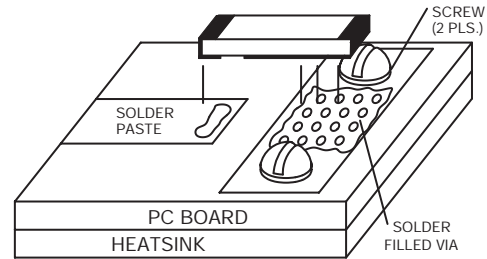
## Typical Performance



## Power Derating



## Suggested Mounting Procedures



1. Solder part in place using 60/40 type solder with controlled temperature iron (700°F).
2. Drill thermal via through PCB and fill with solder, such as 60/40 type.
3. To ensure good thermal connectivity to heat sink, drill and tap heatsink and mount PCB board to heat sink using screws.

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